

HF

Halogen Free

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL RELEASE	09/11'25	Winner

A

B

C

D

E

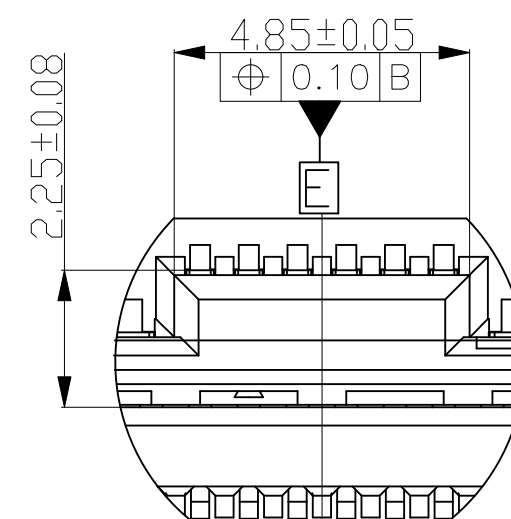
A

B

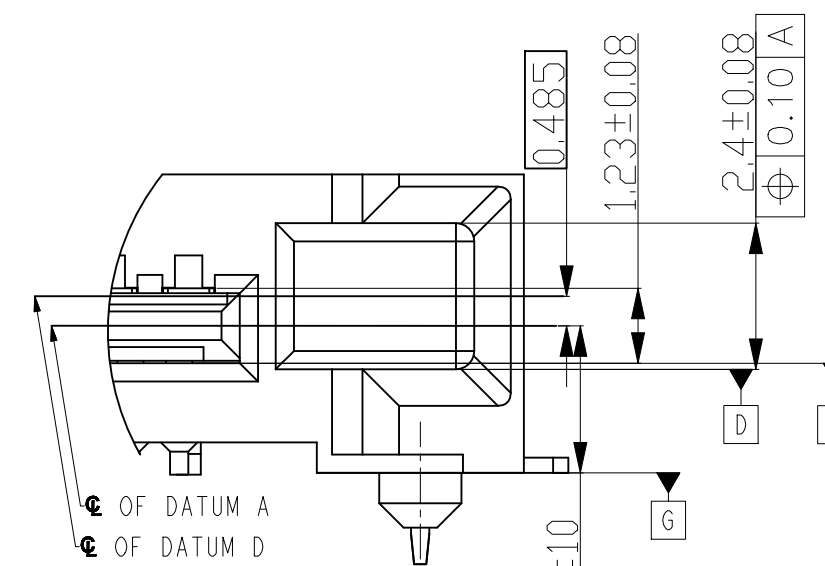
C

D

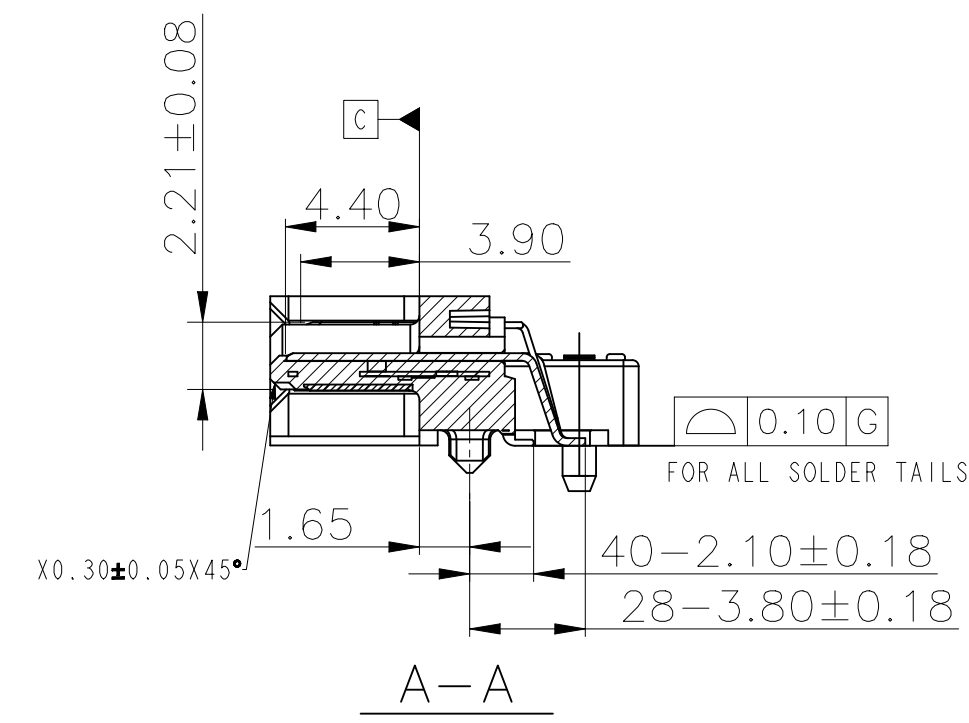
E



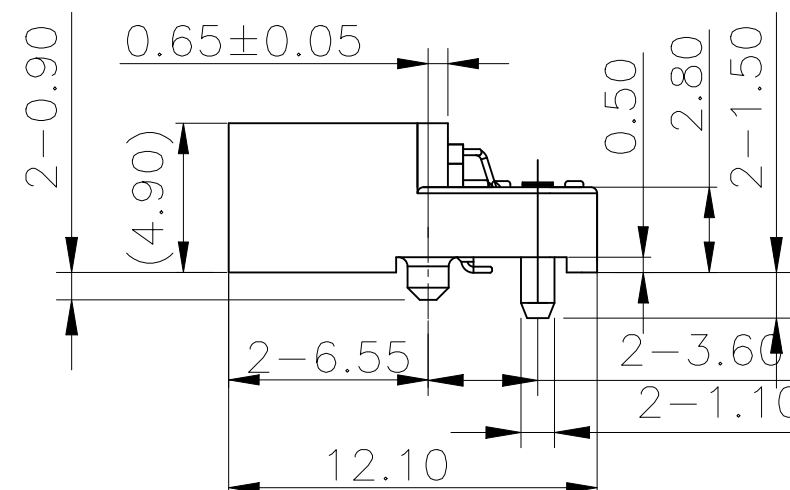
SEE DETAIL A
2:1



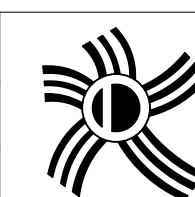
SEE DETAIL B
2:1



A-A



DIM	TOL	DIM	TOL
x.	±0.30	x.	±2°
.x	±0.25	.x	±1°
.xx	±0.20		



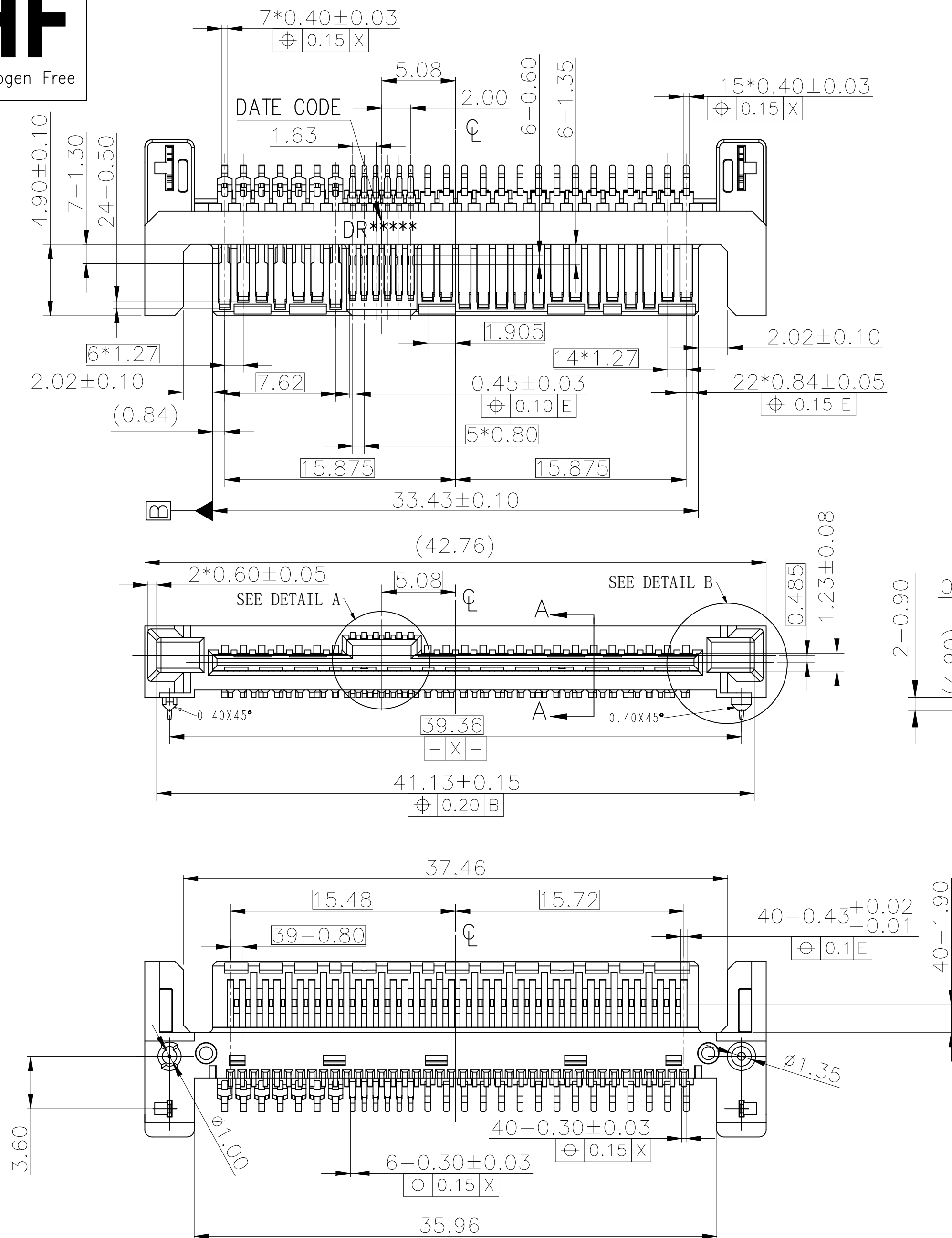
DEREN
SHENZHEN DEREN ELECTRONIC CO., LTD

DRAW NO.
SC2512019-1

REV. A

CUSTOMER DRAWING	DATE	TITLE
DESIGN: Winner	09/11'25	PCIE SAS 68PIN 5.0 PLUG R/A SMT CH=2.4 DIP PEG CONN.
CHECK: LFG	09/11'25	P/N: 562202-003H-100R
APPROVAL: Bill	09/11'25	SHEET: 1/3

SCALE	UNIT
1:1	mm



HF

Halogen Free

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
SEE SHEET 1					

NOTES:

1.MATERIAL

- 1.1.HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK;
- 1.2.CAP: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK;
- 1.3.CONTACT: COPPER ALLOY
- 1.4.PEG: STAINLESS STEEL

2. FINISH:

- 2.1 CONTACT:
0.75um[30u"]MIN, Au PLATING ON CONTACT AREA.
2.03um [80u"] MIN. TIN PLATING ON SOLDER TAIL AREA.
1.27um [50u"] MIN.NICKEL UNDERPLATING ON ALLOVER AREA.
- 2.2 PEG
2.03um [80u"] MIN TIN PLATING OVERALL
1.27um [50u"] MIN NICKEL UNDERPLATING OVERALL

3. ELECTRICAL :

- 3-1.CONTACT CURRENT RATING :
CONTINUOUS CURRENT:1.5A
PEAK CURRENT:2.5A for 1.5s
- 3-2 CONGACT RESISTANCE: 40mΩ MAX.(INITIAL)
- 3-3.OPERATING TEMPERATURE : -55°C TO +85°C
- 3-4.VOLTAGE: 30V MAX.
- 3-5.INSULATION RESISTANCE : 1000 MEGAOHMS MIN.
- 3-6.DIELECTRIC WITHSTANDING VOLTAGE : 400VAC MIN.
- 3-7.LOW LEVEL CONTACT RESISTANCE :

4.MECHANICAL CHARACTERISTICS :

- 4-1.INSERTION FORCE : 65N MAX.
- 4-2.DURABILITY : 500 MATING CYCLES.

5. APPLIED TO REFLOW SOLDERING PROCESS

6. RECOMMENDED STENCIL THICKNESS: 0.15mm min.

7. PART NUMBER DESCRIPTION:

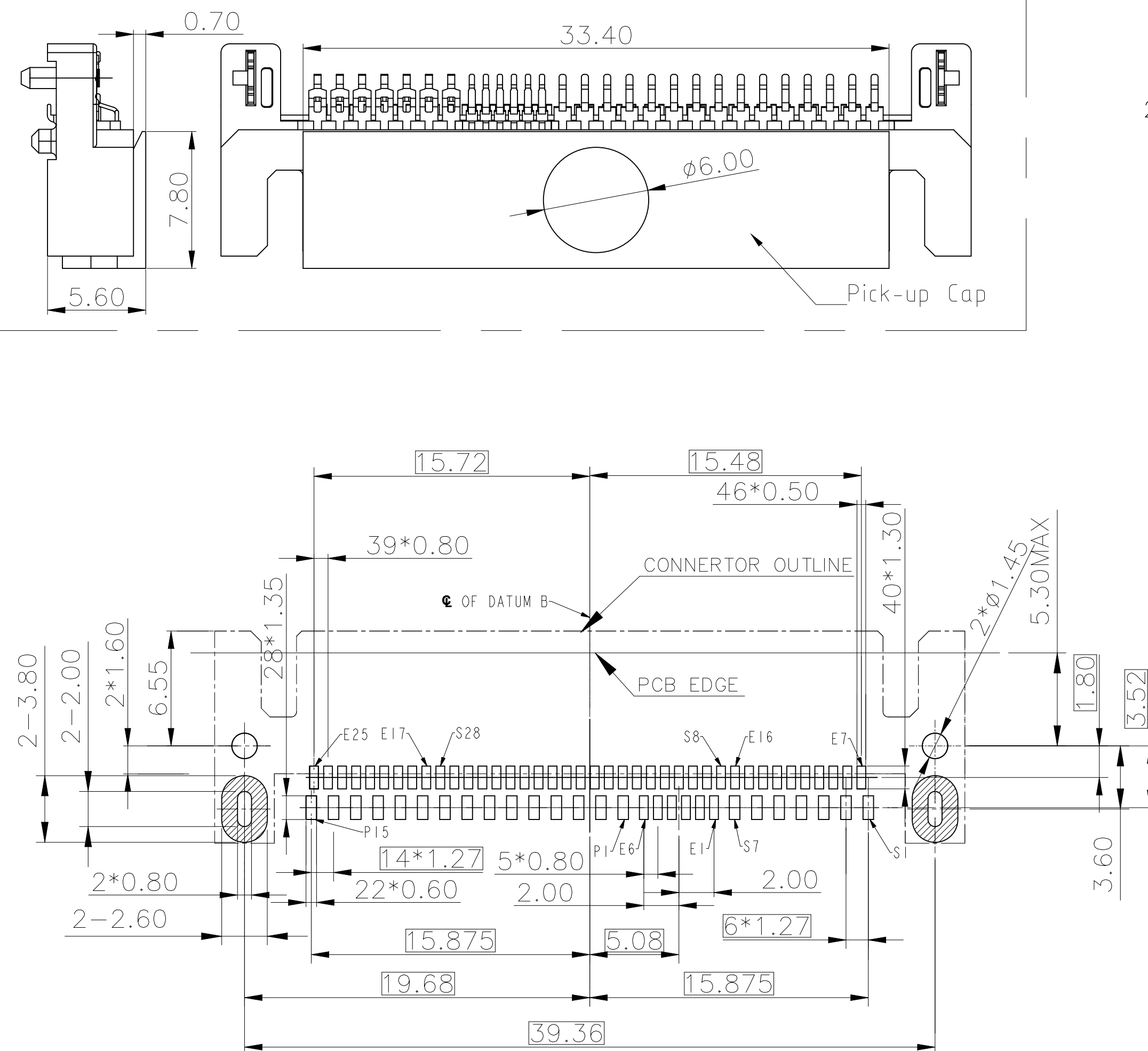
562202-003H-100R

CONTACT PLATING CODE:

- 1: Au 30u"
- 2: Au 15u"
- 3: Gold Flash

LOGO CODE:

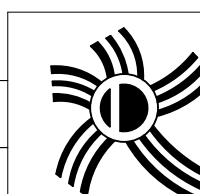
- 0: W/ DEREN LOGO
- 1: W/O LOGO



RECOMMEND P.C.B LAYOUT(COMPONENT SIDE)

TOLERANCES: ±0.05; PCB THICKNESS: 1.6mm(TOP VIEW)

DIM	TOL	DIM	TOL
x.	±0.30	x.	±2°
.x	±0.25	.x	±1°
.xx	±0.15		



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DRAW NO.
SC2512019-1

REV. A

CUSTOMER DRAWING

DESIGN:

CHECK:

APPROVAL:

DATE

Winner 09/11'25

LFG 09/11'25

Bill 09/11'25

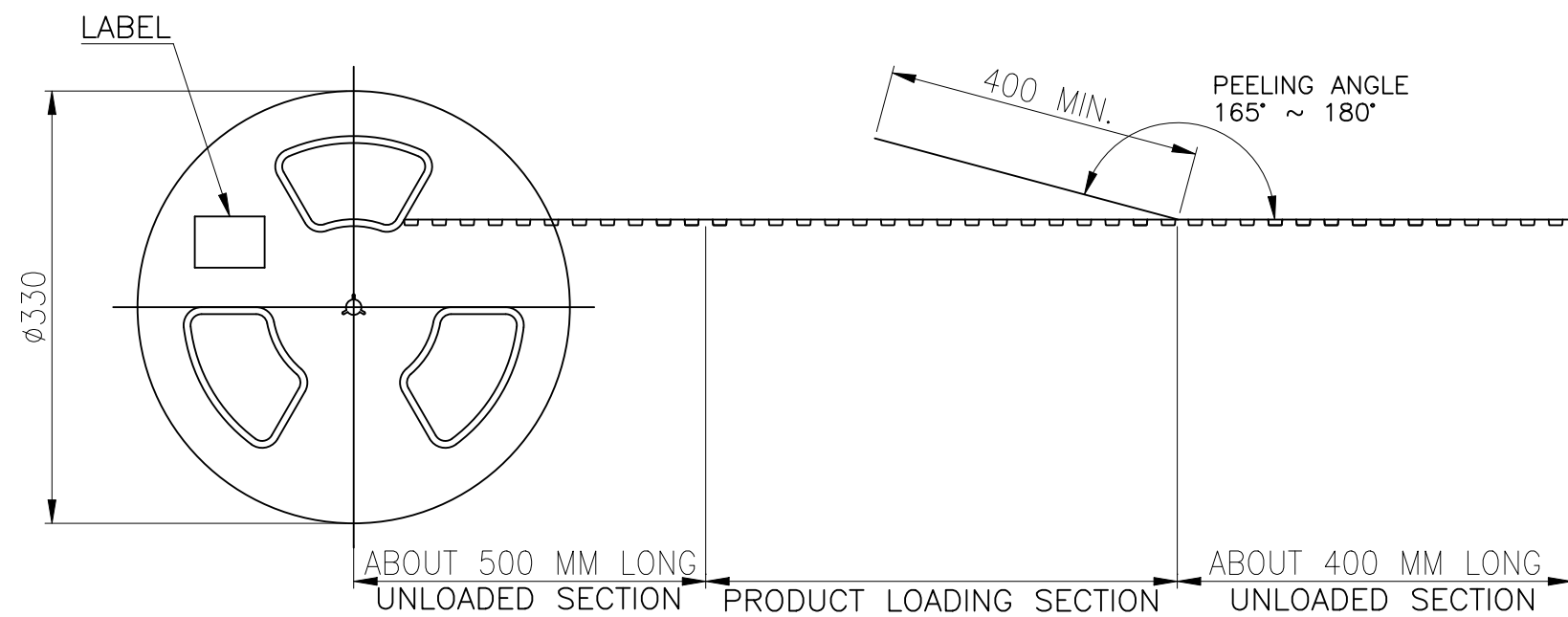
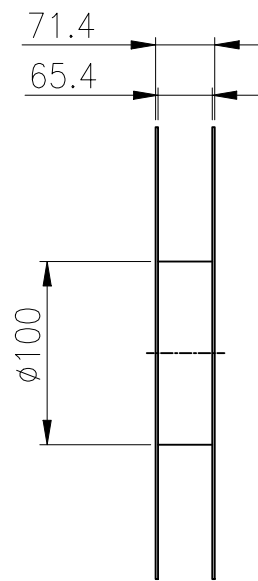
TITLE: PCIE SAS 68PIN 5.0 PLUG R/A
SMT CH=2.4 WITH DIP PEG CONN.

P/N: 562202-003H-100R

SHEET: 2/3

SCALE: 1:1 UNIT: mm

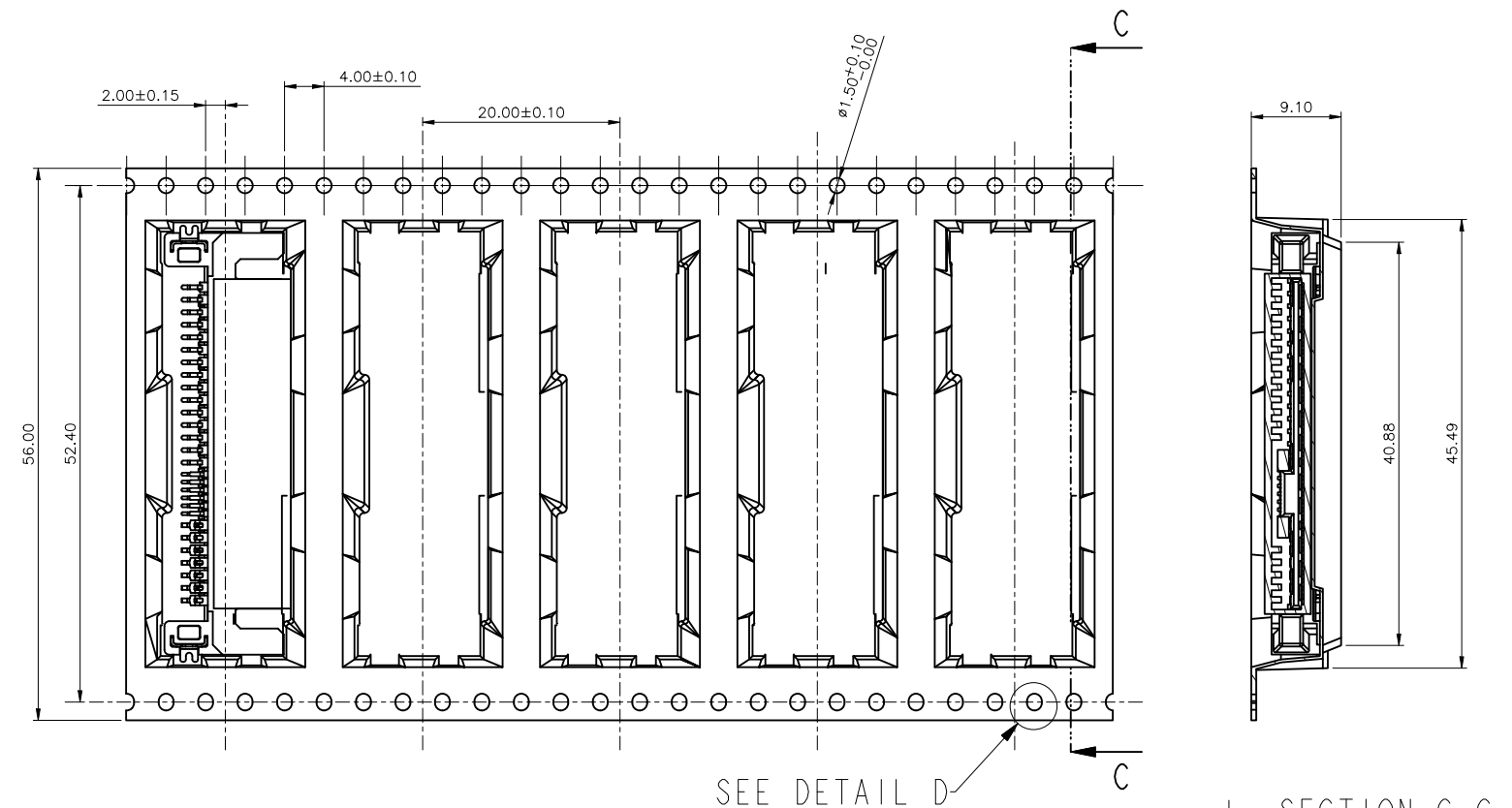
HF
Halogen Free



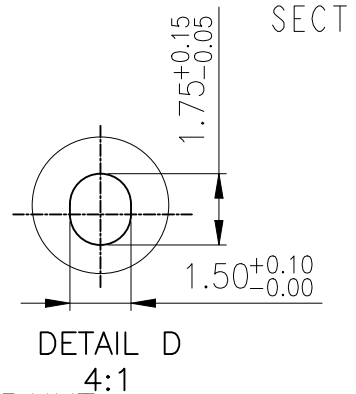
GATHER MATERIAL DIRECTION

INPUT MATERIAL DIRECTION

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
SEE SHEET 1					



DETAIL C
SCALE 1:1

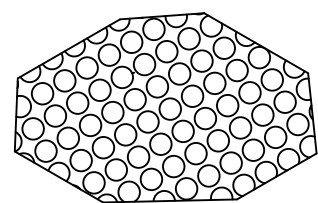


SECTION C-C

PARTITION BOARD
DIMENSIONS:
330 X 330 X 3.5

TAPE & REEL
3 PCS

TOTAL 3 REEL



VOID FILLER

PARTITION BOARD

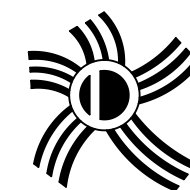
BOX
DIMENSIONS:
335 X 335 X 250
(INNER DIM.)

LABEL

- NOTES : (FOR TAPE & REEL)
PACKAGING MATERIAL IN PLASTIC, RUBBER, INK, PIGMENT AND PAINT
MUST MEET DEREN CONTROLLED SUBSTANCES SPEC.
* CADMIUM AND CADMIUM COMPOUNDS NOT TO EXCEED:
5 PPM.
* LEAD, CADMIUM, CHROM VI AND MERCURY NOT TO EXCEED:
100 PPM (COMBINED).
* CARRIER TAPES, COVER TAPES, REELS AND TAPED COMPONENTS
MUST MEET THE REQUIREMENTS DEFINED PER EIA-481-B.
- MATERIAL :
COVER TAPE : PET, COLOR: CLEAR
CARRIER TAPE : PS
REEL : PS
SHIPPING BOX: CORRUGATED FIBER
 - DIMENSION :
REEL : SEE DRAWING
BOX : SEE DRAWING
 - QUANTITY : SEE TABLE
 - WEIGHT : SEE TABLE
 - PEELING RESISTANCE : 10gf~100gf (for 8mm)
10gf~130gf (for 12mm~56mm)
10gf~150gf (for 72mm)
 - PEELING SPEED : 300mm/MINUTES

450	3	1350
PCS/ TAPE	REELS/ BOX	PCS/BOX

DIM	TOL	DIM	TOL
x.	±0.38	x.	±2°
.x		.x	±1°
.xx	±0.25		
.xxx	±0.20		



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DRAW NO.
SC2512019-1

REV. A

CUSTOMER DRAWING

DESIGN: Winner

CHECK: LFG

APPROVAL: Bill

DATE

09/11'25

09/11'25

09/11'25

TITLE: PCIE SAS 68PIN 5.0 PLUG R/A
SMT CH=2.4 WITH DIP PEG CONN.

P/N: 562202-003H-100R

SHEET: 3/3

SCALE: N/A UNIT: mm